nexperia

Advance Product Change Notification

201704003A

Issue Date: 26-Apr-2017

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia.
For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

Change of bond wire material from Au to Cu for small signal MOSFETs in SOT323

Details of this Planned Change

Scheduled changes affect product types in SOT323 (SC-70) package only.

The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.

Old product: wire material is Au
Changed product: wire material is Cu or Au

The design and materials of all other components will remain unchanged: die, die attach, mold compound, and lead frame. Reliability qualification and full electrical characterization over temperature are performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Plan this Change

Aligning with world technology standards, Nexperia continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Samples can be ordered now and will be shipped with FPCN issue date.

Production

Planned first shipment 01-Oct-2017

Impact

No impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Timing and Logistics

The Self Qualification Report will be ready on 19-Jun-2017.

The Final PCN is planned to be issued on: 19-Jun-2017.

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 26-May-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address DiscrQA.Helpdesk.GA-Products@nexperia.com

At Nexperia B.V we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Nexperia Quality Management Team.

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About Nexperia B.V

We at Nexperia are the efficiency semiconductor company. We deliver over 70 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
BSS84AKW,115	934065305115	BSS84AKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
NX3008PBKW,115	934065636115	NX3008PBKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
BSS138PW,115	934064987115	BSS138PW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
"NX7002AKW,115"	934066297115	NX7002AKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
2N7002BKW,115	934064283115	2N7002BKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
NX3020NAKW,115	934067071115	NX3020NAKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
"NX3008NBKW,115"	934065635115	NX3008NBKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes
BSS138BKW,115	934065731115	BSS138BKW	small signal MOSFET	SOT323	SC-70	RFS	BL MOS Discretes